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SN74CB3Q16811
24-BIT SWITCH WITH PRECHARGED OUTPUTS
2.5-V/3.3-V LOW-VOLTAGE FET BUS SWITCH

SCDS153B−OCTOBER 2003−REVISED MARCH 2005

FEATURES

- **Member of the Texas Instruments Widebus™ Family**
- **SN74CB3Q Bus Switches Are Equivalent to IDTQS3VH Bus Switches**
- **5-V Tolerant I/Os With Device Powered Up or Powered Down**
- **Low and Flat ON-State Resistance (r_{on}) Characteristics Over Operating Range (r_{on} = 5 Ω Typ)**
- **Rail-to-Rail Switching on Data I/O Ports**
    - **0- to 5-V Switching With 3.3-V V_{CC}**
    - **0- to 3.3-V Switching With 2.5-V V_{CC}**
- **B-Port Outputs Are Precharged by Bias Voltage (BIASV) to Minimize Signal Distortion During Live Insertion and Hot Plugging**
- **Supports PCI Hot Plug**
- **Bidirectional Data Flow With Near-Zero Propagation Delay**
- **Low Input/Output Capacitance Minimizes Loading and Signal Distortion ($C_{io(OFF)}$ = 4 pF Typ)**
- **Fast Switching Frequency ($f_{\overline{ON}}$ = 20 MHz Max)**

- **Data and Control Inputs Provide Undershoot Clamp Diodes**
- **Low Power Consumption (I_{CC} = 0.75 mA Typ)**
- **V_{CC} Operating Range From 2.3 V to 3.6 V**
- **Data I/Os Support 0- to 5-V Signaling Levels (0.8 V, 1.2 V, 1.5 V, 1.8 V, 2.5 V, 3.3 V, 5 V)**
- **Control Inputs Can Be Driven by TTL or 5-V/3.3-V CMOS Outputs**
- **I_{off} Supports Partial-Power-Down Mode Operation**
- **Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II**
- **ESD Performance Tested Per JESD 22**
    - **2000-V Human-Body Model (A114-B, Class II)**
    - **1000-V Charged-Device Model (C101)**
- **Supports Both Digital and Analog Applications: PCI Hot Plug, Hot Docking, Memory Interleaving, Bus Isolation, and Low-Distortion Signal Gating**

DESCRIPTION/ORDERING INFORMATION

The SN74CB3Q16811 is a high-bandwidth FET bus switch utilizing a charge pump to elevate the gate voltage of the pass transistor, providing a low and flat ON-state resistance (r_{on}). The low and flat ON-state resistance allows for minimal propagation delay and supports rail-to-rail switching on the data input/output (I/O) ports. The device also features low data I/O capacitance to minimize capacitive loading and signal distortion on the data bus. Specifically designed to support high-bandwidth applications, the SN74CB3Q16811 provides an optimized interface solution ideally suited for broadband communications, networking, and data-intensive computing systems.

ORDERING INFORMATION

T_A	PACKAGE[1]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
−40°C to 85°C	SSOP – DL	Tube	SN74CB3Q16811DL	CB3Q16811
		Tape and reel	SN74CB3Q16811DLR	
	TSSOP – DGG	Tape and reel	SN74CB3Q16811DGGR	CB3Q16811
	TVSOP – DGV	Tape and reel	SN74CB3Q16811DGVR	BW811

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

DESCRIPTION/ORDERING INFORMATION (CONTINUED)

The SN74CB3Q16811 is organized as two 12-bit bus switches with separate output-enable ($1\overline{OE}$, $2\overline{OE}$) inputs. It can be used as two 12-bit bus switches or as one 24-bit bus switch. When $\overline{OE}$ is low, the associated 12-bit bus switch is ON, and the A port is connected to the B port, allowing bidirectional data flow between ports. When $\overline{OE}$ is high, the associated 12-bit bus switch is OFF, and a high-impedance state exists between the A and B ports. The B port is precharged to bias voltage (BIASV) through the equivalent of a 10-kΩ resistor when $\overline{OE}$ is high or if the device is powered down (V_{CC} = 0 V).

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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During insertion (or removal) of a card into (or from) an active bus, the card's output voltage may be close to GND. When the connector pins make contact, the card's parasitic capacitance tries to force the bus signal to GND, creating a possible glitch on the active bus. This glitching effect can be reduced by using a bus switch with precharged bias voltage (BIASV) of the bus switch equal to the input threshold voltage level of the receivers on the active bus. This method ensures that any glitch produced by insertion (or removal) of the card does not cross the input threshold region of the receivers on the active bus, minimizing the effects of live-insertion noise.

This device is fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry prevents damaging current backflow through the device when it is powered down.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.
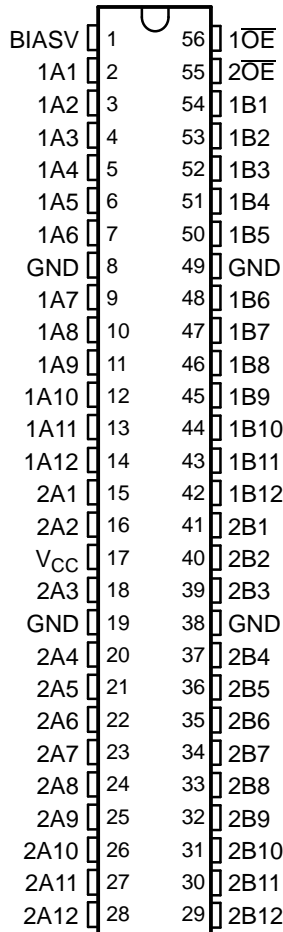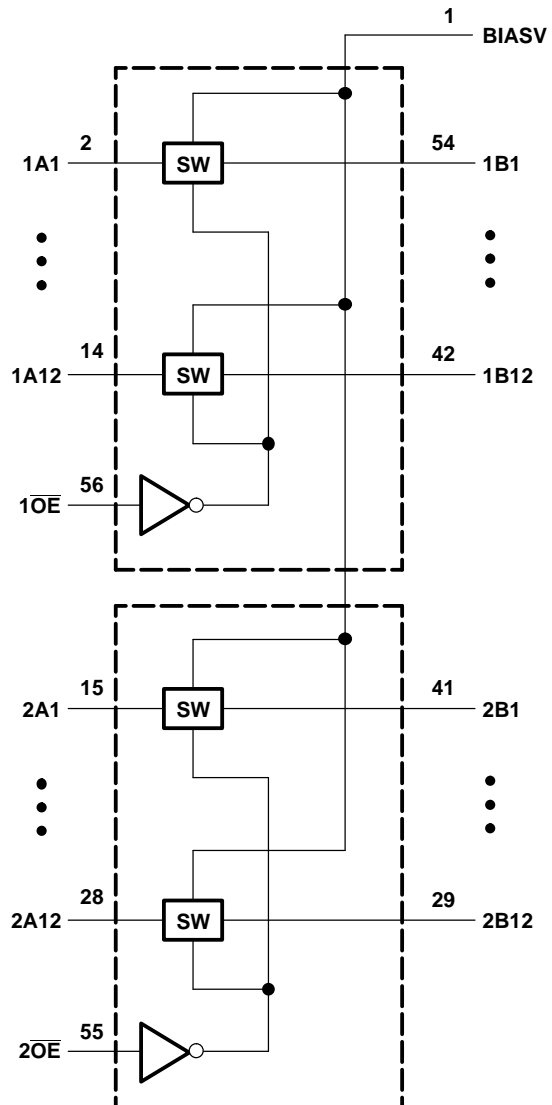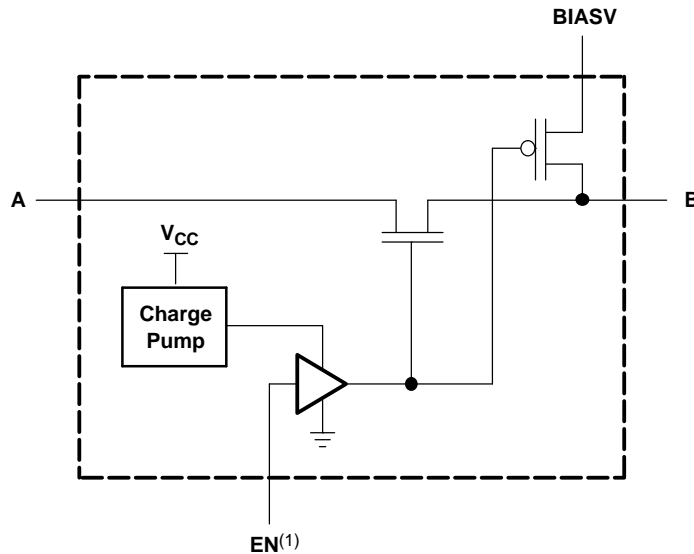
DGG, DGV, OR DL PACKAGE
(TOP VIEW)

BIASV	1	56	1$\overline{OE}$
1A1	2	55	2$\overline{OE}$
1A2	3	54	1B1
1A3	4	53	1B2
1A4	5	52	1B3
1A5	6	51	1B4
1A6	7	50	1B5
GND	8	49	GND
1A7	9	48	1B6
1A8	10	47	1B7
1A9	11	46	1B8
1A10	12	45	1B9
1A11	13	44	1B10
1A12	14	43	1B11
2A1	15	42	1B12
2A2	16	41	2B1
V_{CC}	17	40	2B2
2A3	18	39	2B3
GND	19	38	GND
2A4	20	37	2B4
2A5	21	36	2B5
2A6	22	35	2B6
2A7	23	34	2B7
2A8	24	33	2B8
2A9	25	32	2B9
2A10	26	31	2B10
2A11	27	30	2B11
2A12	28	29	2B12

Table 1. FUNCTION TABLE
(EACH 12-BIT BUS SWITCH)

INPUT $\overline{OE}$	INPUT/OUTPUT A	FUNCTION
L	B	A port = B port
H	Z	Disconnect B port = BIASV

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LOGIC DIAGRAM (POSITIVE LOGIC)

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SIMPLIFIED SCHEMATIC, EACH FET SWITCH (SW)

(1) EN is the internal enable signal applied to the switch.

Absolute Maximum Ratings[1]

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CC}	Supply voltage range		−0.5	4.6	V
BIASV	BIAS supply voltage range		−0.5	7	V
V_{IN}	Control input voltage range[2][3]		−0.5	7	V
$V_{I/O}$	Switch I/O voltage range[2][3][4]		−0.5	7	V
I_{IK}	Control input clamp current	$V_{IN} < 0$		−50	mA
$I_{I/OK}$	I/O port clamp current	$V_{I/O} < 0$		−50	mA
$I_{I/O}$	ON-state switch current[5]			±64	mA
	Continuous current through V_{CC} or GND			±100	mA
θ_{JA}	Package thermal impedance[6]	DGG package		64	°C/W
		DGV package		48	
		DL package		56	
T_{stg}	Storage temperature range		−65	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) All voltages are with respect to ground, unless otherwise specified.
(3) The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
(4) V_I and V_O are used to denote specific conditions for $V_{I/O}$.
(5) I_I and I_O are used to denote specific conditions for $I_{I/O}$.
(6) The package thermal impedance is calculated in accordance with JESD 51-7.

Recommended Operating Conditions[1]

			MIN	MAX	UNIT
V_{CC}	Supply voltage		2.3	3.6	V
BIASV	Bias voltage		0	5	V
V_{IH}	High-level control input voltage	V_{CC} = 2.3 V to 2.7 V	1.7	5.5	V
		V_{CC} = 2.7 V to 3.6 V	2	5.5	
V_{IL}	Low-level control input voltage	V_{CC} = 2.3 V to 2.7 V	0	0.7	V
		V_{CC} = 2.7 V to 3.6 V	0	0.8	
$V_{I/O}$	Data input/output voltage		0	5.5	V
T_A	Operating free-air temperature		−40	85	°C

(1) All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

Electrical Characteristics[1]

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS			MIN	TYP[2]	MAX	UNIT
V_{IK}		V_{CC} = 3.6 V,	I_I = −18 mA				−1.8	V
I_{IN}	Control inputs	V_{CC} = 3.6 V,	V_{IN} = 0 to 5.5 V				±1	µA
I_O	B port	V_{CC} = 3.V,	BIASV = 2.4 V, V_O = 0,	Switch OFF, V_{IN} = V_{CC} or GND		0.2		mA
I_{OZ}[3]		V_{CC} = 3.6 V,	V_O = 0 to 5.5 V, V_I = 0,	Switch OFF, V_{IN} = V_{CC} or GND			±1	µA
I_{off}		V_{CC} = 0,	V_O = 0 to 5.5 V,	V_I = 0			1	µA
I_{CC}		V_{CC} = 3.6 V,	$I_{I/O}$ = 0, Switch ON or OFF,	V_{IN} = V_{CC} or GND		1	3	mA
ΔI_{CC}[4]	Control inputs	V_{CC} = 3.6 V,	One input at 3 V,	Other inputs at V_{CC} or GND			30	µA
I_{CCD}[5]	Per control input	V_{CC} = 3.6 V,	A and B ports open, Control input switching at 50% duty cycle			0.38	0.45	mA/ MHz
C_{in}	Control inputs	V_{CC} = 3.3 V,	V_{IN} = 5.5 V, 3.3 V, or 0			3.5	5	pF
$C_{io(OFF)}$	A port	V_{CC} = 3.3 V,	Switch OFF, V_{IN} = V_{CC} or GND,	$V_{I/O}$ = 5.5 V, 3.3 V, or 0		4	5	pF
$C_{io(ON)}$		V_{CC} = 3.3 V,	Switch ON, V_{IN} = V_{CC} or GND,	$V_{I/O}$ = 5.5 V, 3.3 V, or 0		10	12.5	pF
r_{on}[6]		V_{CC} = 2.3 V, TYP at V_{CC} = 2.5 V	V_I = 0,	I_O = 30 mA		5	8	Ω
			V_I = 1.7 V,	I_O = −15 mA		5	9	
		V_{CC} = 3 V	V_I = 0,	I_O = 30 mA		5	6.5	
			V_I = 2.4 V,	I_O = −15 mA		5	8	

(1) V_{IN} and I_{IN} refer to control inputs. V_I, V_O, I_I, and I_O refer to data pins.
(2) All typical values are at V_{CC} = 3.3 V (unless otherwise noted), T_A = 25°C.
(3) For I/O ports, the parameter I_{OZ} includes the input leakage current.
(4) This is the increase in supply current for each input that is at the specified TTL voltage level, rather than V_{CC} or GND.
(5) This parameter specifies the dynamic power-supply current associated with the operating frequency of a single control input (see Figure 2).
(6) Measured by the voltage drop between the A and B terminals at the indicated current through the switch. ON-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

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Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 3)

PARAMETER	FROM (INPUT)	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 2.5 V ± 0.2 V		V_{CC} = 3.3 V ± 0.3 V		UNIT
				MIN	MAX	MIN	MAX	
$f_{\overline{OE}}$[1]		$\overline{OE}$	A or B		10		20	MHz
t_{pd}[2]		A or B	B or A		0.09		0.15	ns
t_{PZH}	BIASV = GND	$\overline{OE}$	A or B	1.5	8	1.5	8	ns
t_{PZL}	BIASV = 3 V			1.5	8	1.5	8	
t_{PHZ}	BIASV = GND	$\overline{OE}$	A or B	1	7.5	1	7.5	ns
t_{PLZ}	BIASV = 3 V			1	7.5	1	7.5	

(1) Maximum switching frequency for control input ($V_O > V_{CC}$, V_I = 5 V, $R_L \geq 1$ MΩ, C_L = 0)
(2) The propagation delay is the calculated RC time constant of the typical ON-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).
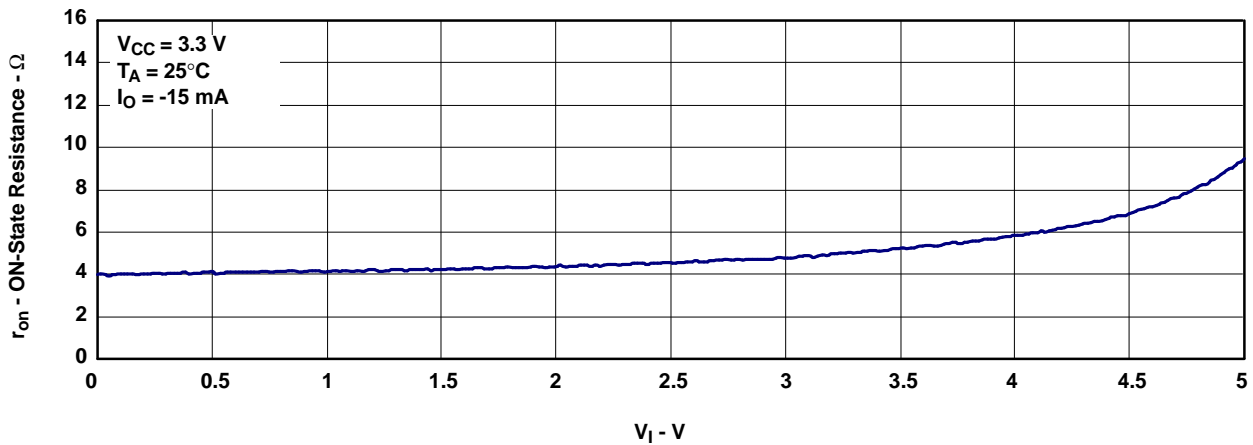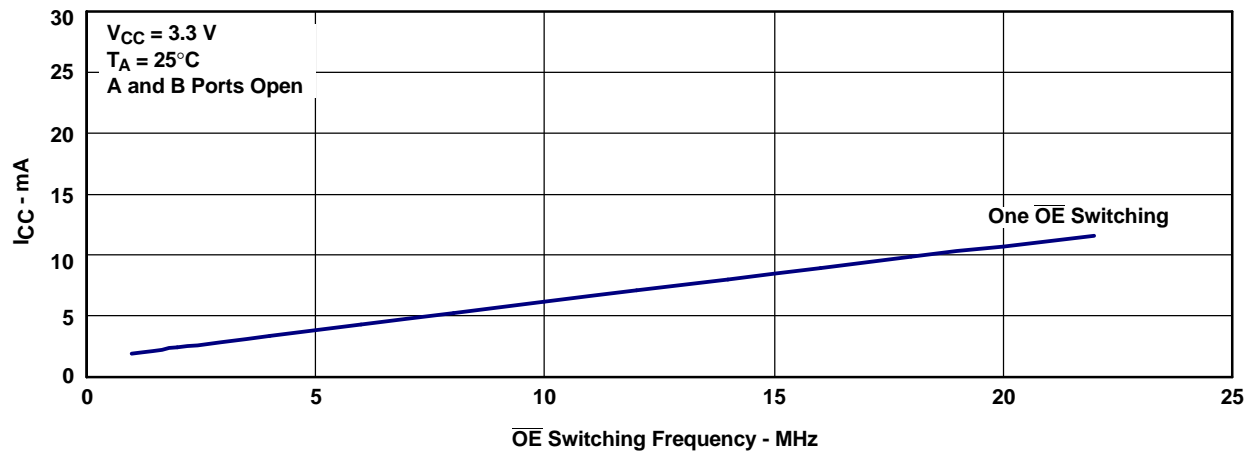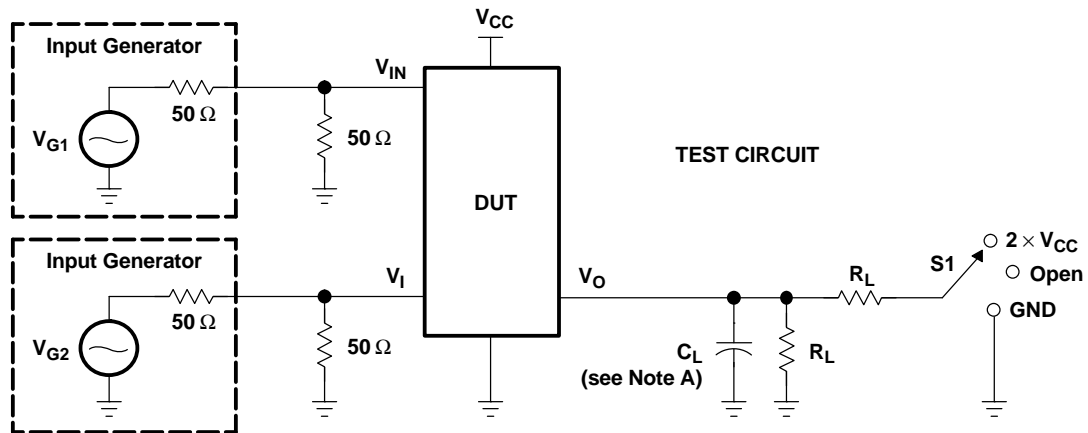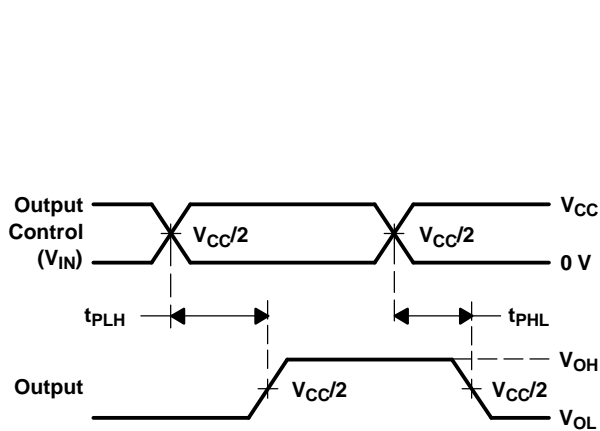

Figure 1. Typical r_{on} vs V_I


Figure 2. Typical I_{CC} vs $\overline{OE}$ Switching Frequency

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PARAMETER MEASUREMENT INFORMATION

TEST	V_{CC}	S1	R_L	V_I	C_L	V_Δ
$t_{pd(s)}$	2.5 V ± 0.2 V	Open	500 Ω	V_{CC} or GND	30 pF	
	3.3 V ± 0.3 V	Open	500 Ω	V_{CC} or GND	50 pF	
t_{PLZ}/t_{PZL}	2.5 V ± 0.2 V	2 × V_{CC}	500 Ω	GND	30 pF	0.15 V
	3.3 V ± 0.3 V	2 × V_{CC}	500 Ω	GND	50 pF	0.3 V
t_{PHZ}/t_{PZH}	2.5 V ± 0.2 V	GND	500 Ω	V_{CC}	30 pF	0.15 V
	3.3 V ± 0.3 V	GND	500 Ω	V_{CC}	50 pF	0.3 V

VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES ($t_{pd(s)}$)
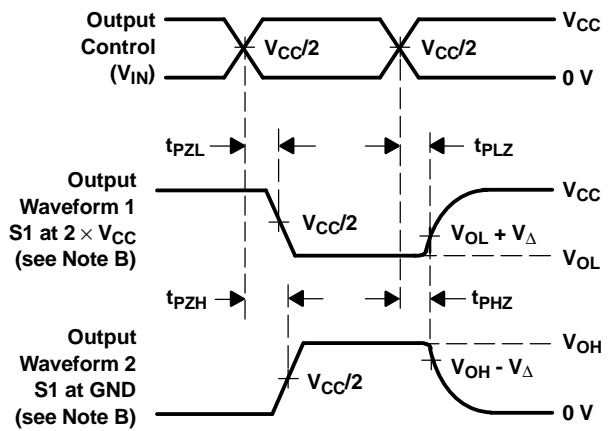
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

NOTES: A. C_L includes probe and jig capacitance.
    B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control.
       Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
    C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
    D. The outputs are measured one at a time, with one transition per measurement.
    E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
    F. t_{PZL} and t_{PZH} are the same as t_{en}.
    G. t_{PLH} and t_{PHL} are the same as $t_{pd(s)}$. The tpd propagation delay is the calculated RC time constant of the typical ON-state resistance
       of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).
    H. All parameters and waveforms are not applicable to all devices.

Figure 3. Test Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN74CB3Q16811DGGR	Active	Production	TSSOP (DGG) | 56	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CB3Q16811
SN74CB3Q16811DGGR.B	Active	Production	TSSOP (DGG) | 56	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CB3Q16811
SN74CB3Q16811DGVR	Active	Production	TVSOP (DGV) | 56	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	BW811
SN74CB3Q16811DGVR.B	Active	Production	TVSOP (DGV) | 56	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	BW811

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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TAPE AND REEL INFORMATION

REEL DIMENSIONS

Reel Diameter

Reel Width (W1)

TAPE DIMENSIONS

Cavity

A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

Sprocket Holes

User Direction of Feed

Pocket Quadrants

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74CB3Q16811DGGR	TSSOP	DGG	56	2000	330.0	24.4	8.9	14.7	1.4	12.0	24.0	Q1
SN74CB3Q16811DGVR	TVSOP	DGV	56	2000	330.0	24.4	6.8	11.7	1.6	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74CB3Q16811DGGR	TSSOP	DGG	56	2000	356.0	356.0	45.0
SN74CB3Q16811DGVR	TVSOP	DGV	56	2000	356.0	356.0	45.0

DL (R−PDSO−G56)   PLASTIC SMALL−OUTLINE PACKAGE

0.025 (0,635)

0.0135 (0,343)
0.008 (0,203)

⊕ 0.005 (0,13) Ⓜ

56   29

0.420 (10,67)
0.395 (10,03)

0.299 (7,59)
0.291 (7,39)

0.010 (0,25)
0.005 (0,13)

Gage Plane

0.010 (0,25)

0°−8°

0.040 (1,02)
0.020 (0,51)

1   28

0.730 (18,54)
0.720 (18,29)

0.110 (2,79) MAX   0.008 (0,20) MIN

Seating Plane

⬛ 0.004 (0,10)

4040048−4/F   05/13

NOTES: A.   All linear dimensions are in inches (millimeters).
          B.   This drawing is subject to change without notice.
          C.   Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
          D.   Falls within JEDEC MO−118

PowerPAD is a trademark of Texas Instruments.

8.3 / 7.9 TYP

A

PIN 1 ID AREA

54X 0.5

56

14.1 / 13.9 NOTE 3

2X 13.5

28

29

B

6.2 / 6.0

56X 0.27 / 0.17

⊕ | 0.08 Ⓜ | C | A Ⓢ | B Ⓢ

C

SEATING PLANE

⌒ | 0.1 | C

1.2 MAX

(0.15) TYP

SEE DETAIL A

GAGE PLANE

0.25

0° - 8°

0.75 / 0.50

0.15 / 0.05

DETAIL A
TYPICAL

4222167/A 07/2015

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-153.

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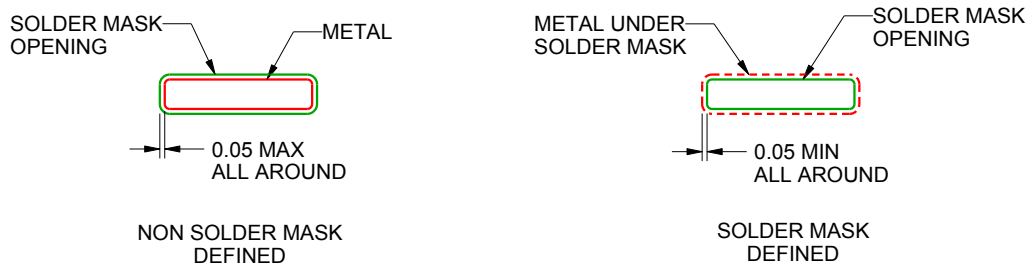www.ti.com

56X (1.5)

SYMM

1

56X (0.3)

56

54X (0.5)

(R0.05)
TYP

SYMM

28

29

(7.5)

LAND PATTERN EXAMPLE
SCALE:6X

SOLDER MASK
OPENING

METAL

METAL UNDER
SOLDER MASK

SOLDER MASK
OPENING

0.05 MAX
ALL AROUND

0.05 MIN
ALL AROUND

NON SOLDER MASK
DEFINED

SOLDER MASK
DEFINED

SOLDER MASK DETAILS

4222167/A   07/2015

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

56X (1.5)

1

56X (0.3)

54X (0.5)

(R0.05) TYP

SYMM

56

SYMM

28

29

(7.5)

SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4222167/A   07/2015

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate
   design recommendations.
8. Board assembly site may have different recommendations for stencil design.

DGV (R-PDSO-G**)   **PLASTIC SMALL-OUTLINE**

24 PINS SHOWN

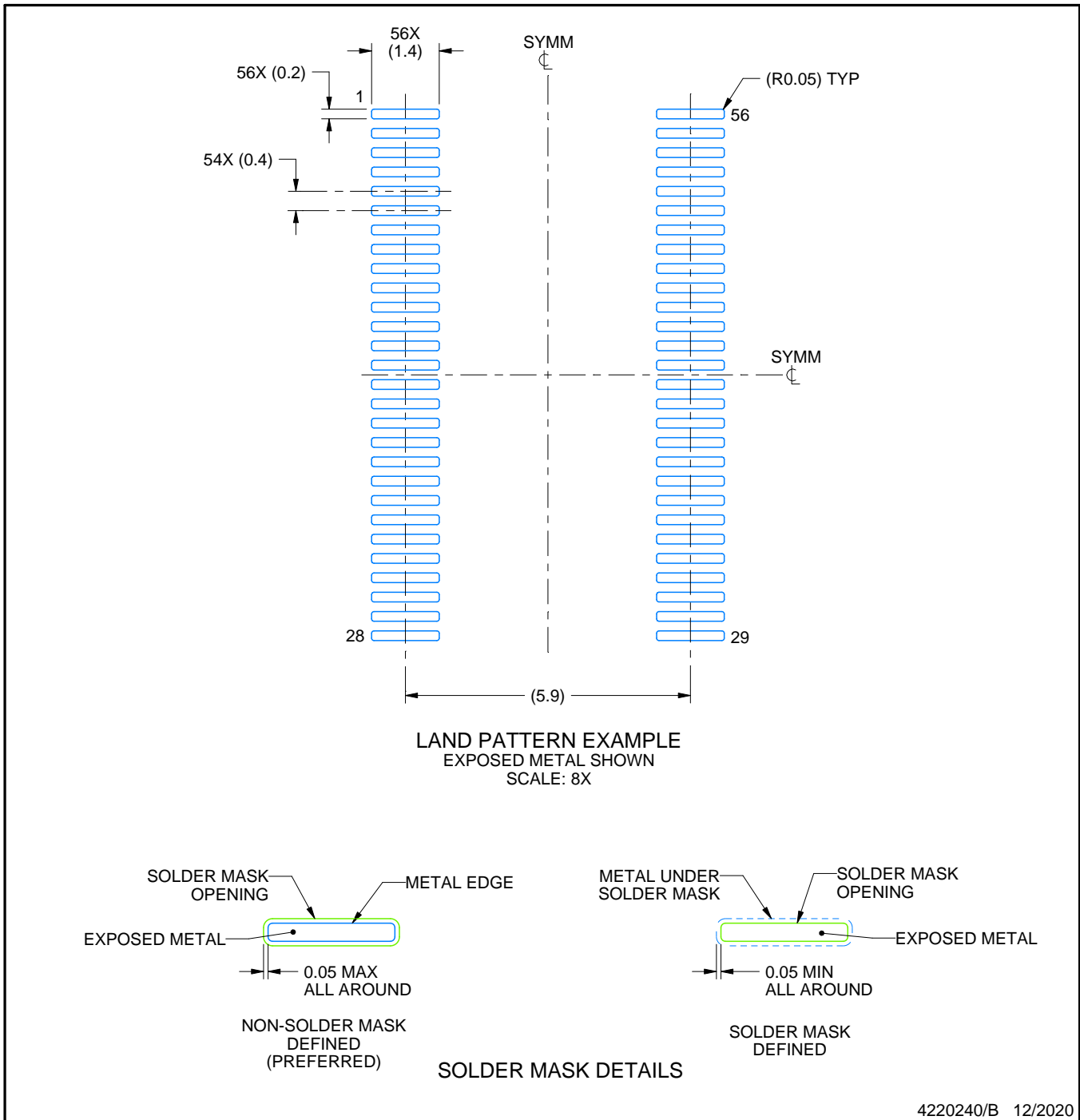| PINS ** DIM	14	16	20	24	38	48	56
A MAX	3,70	3,70	5,10	5,10	7,90	9,80	11,40
A MIN	3,50	3,50	4,90	4,90	7,70	9,60	11,20

4073251/E 08/00

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
D. Falls within JEDEC: 24/48 Pins – MO-153
14/16/20/56 Pins – MO-194

6.6
6.2 TYP

A

PIN 1 INDEX
AREA

1

54X 0.4

56

2X

10.8

11.4
11.2
NOTE 3

28

29

56X 0.23
0.13

$\oplus$ 0.1 Ⓜ C A B

B

4.5
4.3
NOTE 4

C

0.08 C

SEATING
PLANE

(0.15) TYP

SEE DETAIL A

0.25

GAGE PLANE

0°-8°

0.75
0.50

1.2
1.1

0.15
0.05

DETAIL A
TYPICAL

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NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-194.

56X
(1.4)

SYMM

56X (0.2)

1

(R0.05) TYP

56

54X (0.4)

SYMM

28

29

(5.9)

LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 8X

SOLDER MASK
OPENING

METAL EDGE

EXPOSED METAL

0.05 MAX
ALL AROUND

NON-SOLDER MASK
DEFINED
(PREFERRED)

METAL UNDER
SOLDER MASK

SOLDER MASK
OPENING

EXPOSED METAL

0.05 MIN
ALL AROUND

SOLDER MASK
DEFINED

SOLDER MASK DETAILS

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NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 8X

4220240/B   12/2020
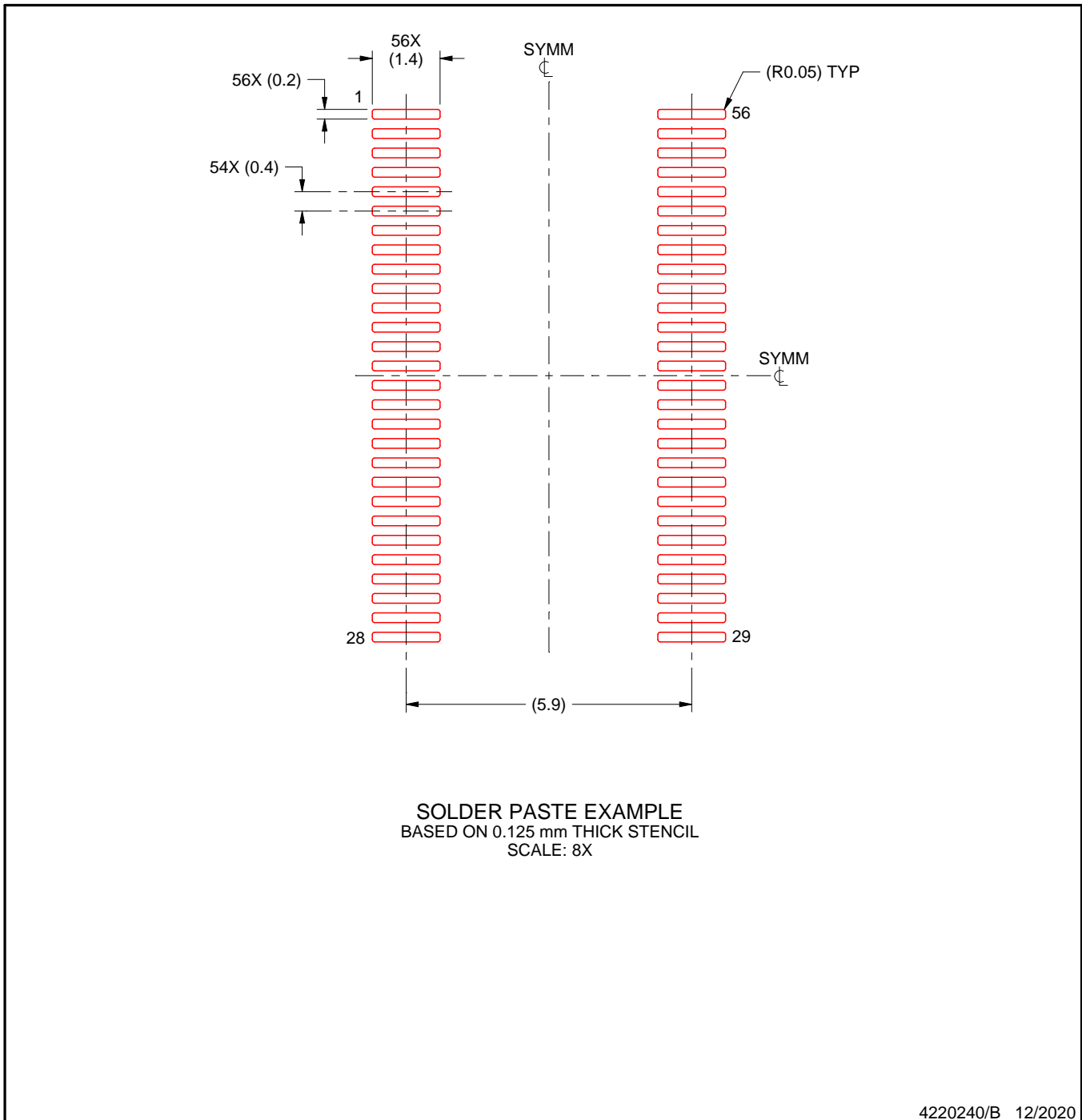
NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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